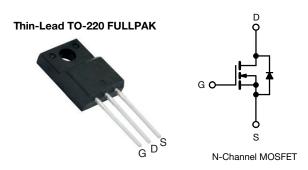


E Series Power MOSFET



| PRODUCT SUMMA | RY | |
|--|------------------------|------|
| V _{DS} (V) at T _J max. | 850 |) |
| R _{DS(on)} typ. (Ω) at 25 °C | V _{GS} = 10 V | 0.25 |
| Q _g max. (nC) | 122 | 2 |
| Q _{gs} (nC) | 14 | |
| Q _{gd} (nC) | 23 | |
| Configuration | Sing | le |

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

| ORDERING INFORMATION | |
|---------------------------------|--------------------------|
| Package | Thin-Lead TO-220 FULLPAK |
| Lead (Pb)-free | SiHA17N80E-E3 |
| Lead (Pb)-free and halogen-free | SiHA17N80E-GE3 |

| ABSOLUTE MAXIMUM RATINGS (T _C | = 25 °C, unl | ess otherwis | se noted) | | | |
|--|--|---|-----------------------------------|-------------|-------|--|
| PARAMETER | | | SYMBOL | LIMIT | UNIT | |
| Drain-source voltage | | V_{DS} | 800 | V | | |
| Gate-source voltage | | V_{GS} | ± 30 | 1 v | | |
| Continuous drain current (T _{.I} = 150 °C) ^e | V _{GS} at 10 V | T _C = 25 °C T _C = 100 °C | 1 | 6 | | |
| Continuous drain current (1) = 150 °C) | V _{GS} at 10 V | T _C = 100 °C | I _D | 4 | Α | |
| Pulsed drain current ^a | | | I _{DM} | 45 | | |
| ear derating factor 0.2 | | 0.28 | W/°C | | | |
| Single pulse avalanche energy b | | E _{AS} | 353 | mJ | | |
| Maximum power dissipation | Maximum power dissipation | | P_{D} | 35 | W | |
| Operating junction and storage temperature range | | | T _J , T _{stg} | -55 to +150 | °C | |
| Drain-source voltage slope | T _J = 125 °C | | dV/dt | 70 | V/ns | |
| Reverse diode dV/dt ^d | | | uv/di | 5.1 | V/IIS | |
| Soldering recommendations (peak temperature) c | ring recommendations (peak temperature) c For 10 s 300 | | °C | | | |
| Mounting torque | M3 s | screw | | 0.6 | Nm | |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 5.0 A c. 1.6 mm from case

- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C
- Limited by maximum junction temperature



Vishay Siliconix

| THERMAL RESISTANCE RATI | NGS | | | |
|----------------------------------|------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum junction-to-ambient | R_{thJA} | - | 65 | °C/W |
| Maximum junction-to-case (drain) | R_{thJC} | - | 3.6 | C/VV |

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|---|---|------|------|-------|------|
| Static | | - | | | | | • |
| Drain-source breakdown voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$ | | 800 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Referenc | Reference to 25 °C, I _D = 1 mA | | 1.08 | - | V/°C |
| Gate-source threshold Voltage (N) | V _{GS(th)} | V _{DS} = | = V _{GS} , I _D = 250 μA | 2.0 | - | 4.0 | V |
| Coto come lockers | | $V_{GS} = \pm 20 \text{ V}$ | | ı | - | ± 100 | nA |
| Gate-source leakage | I _{GSS} | | $V_{GS} = \pm 30 \text{ V}$ | - | - | ± 1 | μΑ |
| Z | | V _{DS} = | V _{DS} = 800 V, V _{GS} = 0 V | | - | 1 | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 640 \ | /, V _{GS} = 0 V, T _J = 125 °C | - | - | 10 | μA |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 8.5 A | ı | 0.25 | 0.29 | Ω |
| Forward transconductance | 9 _{fs} | V_{DS} | = 30 V, I _D = 8.5 A | - | 8.7 | - | S |
| Dynamic | | • | | | | | |
| Input capacitance | C _{iss} | V _{GS} = 0 V, | | - | 2408 | - | pF |
| Output capacitance | C _{oss} | 1 | $V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ | | 81 | - | |
| Reverse transfer capacitance | C _{rss} | f = 1 MHz | | - | 9 | - | |
| Effective output capacitance, energy related ^a | $C_{o(er)}$ | V _{DS} = 0 V to 480 V, V _{GS} = 0 V | | - | 58 | - | |
| Effective output capacitance, time related ^b | C _{o(tr)} | | | - | 296 | - | |
| Total gate charge | Qg | | - | 61 | 122 | | |
| Gate-source charge | Q_{gs} | V _{GS} = 10 V | $I_D = 8.5 \text{ A}, V_{DS} = 480 \text{ V}$ | - | 14 | - | nC |
| Gate-drain charge | Q _{gd} | 7 | | - | 23 | - | |
| Turn-on delay time | t _{d(on)} | | | - | 22 | 44 | |
| Rise time | t _r | $V_{DD} = 480 \text{ V}, I_{D} = 8.5 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$ | | - | 24 | 48 | ns |
| Turn-off delay time | t _{d(off)} | | | - | 71 | 142 | |
| Fall time | t _f | | | - | 26 | 52 | |
| Gate input resistance | R_g | f = 1 MHz, open drain | | 0.3 | 0.7 | 1.4 | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | | |
| Continuous source-drain diode current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 15 | |
| Pulsed diode forward current | I _{SM} | | | - | - | 45 | A |
| Diode forward voltage | V _{SD} | T _J = 25 °C | T _J = 25 °C, I _S = 8.5 A, V _{GS} = 0 V | | - | 1.2 | V |
| Reverse recovery time | t _{rr} | T _J = 25 °C, I _F = I _S = 8.5 A, dl/dt = 100 A/ μ s, V _R = 25 V | | - | 416 | 832 | ns |
| Reverse recovery charge | Q _{rr} | | | - | 6.4 | 12.8 | μC |
| Reverse recovery current | I _{RRM} | | | - | 27 | _ | Α |

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

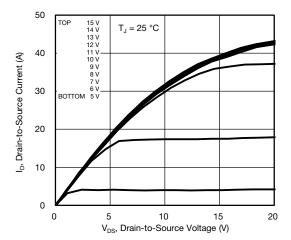


Fig. 1 - Typical Output Characteristics

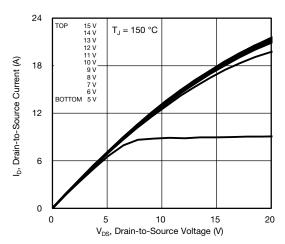


Fig. 2 - Typical Output Characteristics

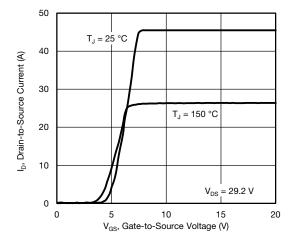


Fig. 3 - Typical Transfer Characteristics

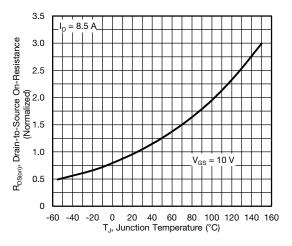


Fig. 4 - Normalized On-Resistance vs. Temperature

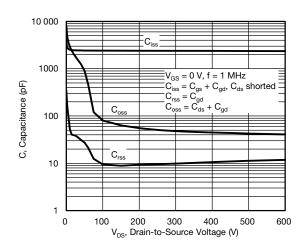


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

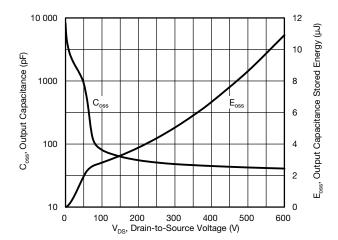


Fig. 6 - Coss and Eoss vs. VDS



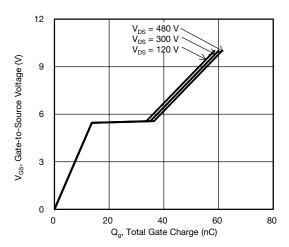


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

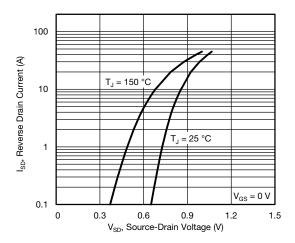


Fig. 8 - Typical Source-Drain Diode Forward Voltage

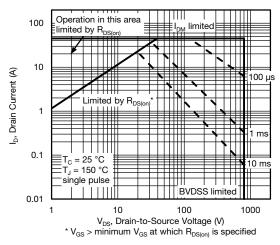


Fig. 9 - Maximum Safe Operating Area

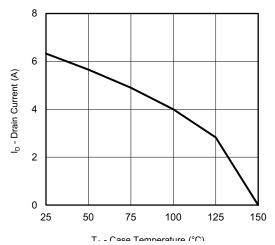


Fig. 10 - Maximum Drain Current vs. Case Temperature

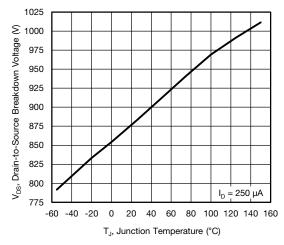


Fig. 11 - Temperature vs. Drain-to-Source Voltage



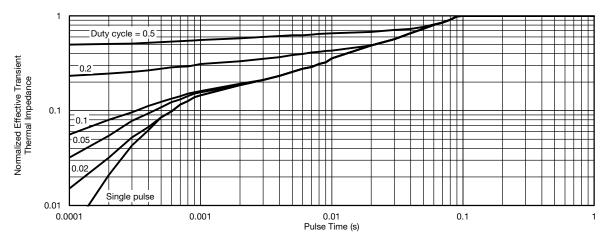


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

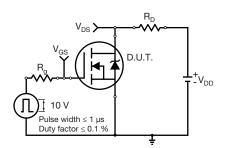


Fig. 13 - Switching Time Test Circuit

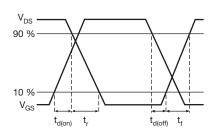


Fig. 14 - Switching Time Waveforms

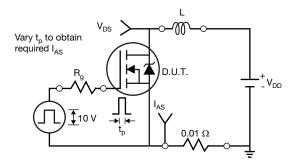


Fig. 15 - Unclamped Inductive Test Circuit

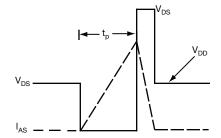


Fig. 16 - Unclamped Inductive Waveforms

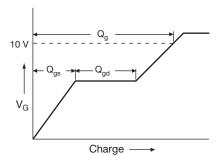


Fig. 17 - Basic Gate Charge Waveform

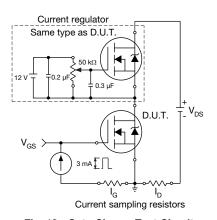
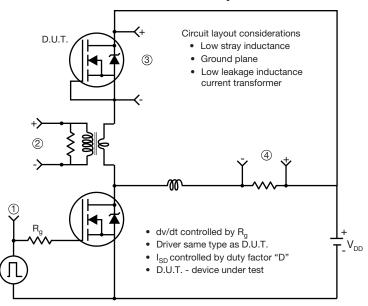


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



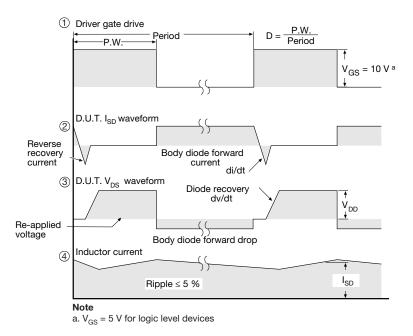
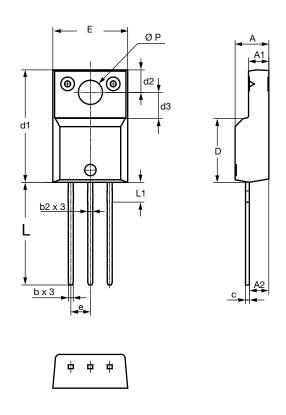


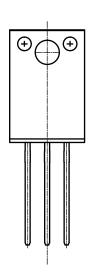
Fig. 19 - For N-Channel

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Vishay Siliconix

TO-220 FULLPAK Thin Lead





| SYMBOL | | DIMEN | ISIONS | | |
|--------|--------|--------|--------|-------|--|
| | MILLIN | IETERS | INCHES | | |
| | MIN. | MAX. | MIN. | MAX. | |
| Α | 4.30 | 4.70 | 0.169 | 0.185 | |
| A1 | 2.50 | 2.90 | 0.098 | 0.114 | |
| A2 | 2.40 | 2.80 | 0.094 | 0.110 | |
| b | 0.60 | 0.80 | 0.024 | 0.031 | |
| b2 | 0.60 | 0.90 | 0.024 | 0.035 | |
| С | = | 0.60 | - | 0.024 | |
| D | 8.30 | 8.70 | 0.327 | 0.342 | |
| d1 | 14.70 | 15.30 | 0.579 | 0.602 | |
| d2 | 2.90 | 3.10 | 0.114 | 0.122 | |
| d3 | 3.30 | 3.70 | 0.130 | 0.146 | |
| Е | 9.70 | 10.30 | 0.382 | 0.406 | |
| е | 2.50 | 2.70 | 0.098 | 0.106 | |
| L | 13.40 | 13.80 | 0.528 | 0.543 | |
| L1 | 1.00 | 2.80 | 0.039 | 0.110 | |
| ØP | 3.00 | 3.40 | 0.118 | 0.134 | |

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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